

## Description

The VSM3401BY uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

## General Features

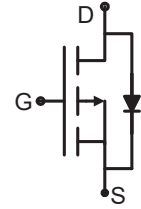
- $V_{DS} = -30V, I_D = -4.4A$   
 $R_{DS(ON)} < 70m\Omega @ V_{GS} = -2.5V$   
 $R_{DS(ON)} < 55m\Omega @ V_{GS} = -4.5V$   
 $R_{DS(ON)} < 45m\Omega @ V_{GS} = -10V$
- High power and current handling capability
- Lead free product is acquired
- Surface mount package

## Application

- PWM applications
- Load switch
- Power management



SOT-23-3



Schematic Diagram

## Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM3401BY-S2	VSM3401BY	SOT-23-3	Ø180mm	8 mm	3000 units

## Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous	$I_D$	-4.4	A
Drain Current-Continuous( $T_C = 100^\circ C$ )	$I_D(100^\circ C)$	-3.1	A
Drain Current-Pulsed <sup>(Note 1)</sup>	$I_{DM}$	-30	A
Maximum Power Dissipation	$P_D$	1.3	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ C$

## Thermal Characteristic

Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	$R_{\theta JA}$	96	$^\circ C/W$
---	-----------------	----	--------------

## Electrical Characteristics ( $T_A = 25^\circ C$ unless otherwise noted)

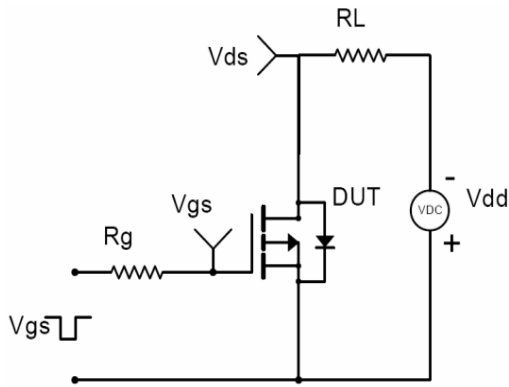
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30		-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -24V, V_{GS} = 0V$	-	-	-1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 12V, V_{DS} = 0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.6	-0.9	-1.2	V

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-4A	-	33	45	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3A	-	37.5	55	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-2A		55	70	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5V,I <sub>D</sub> =-4A	-	10	-	S
Dynamic Characteristics <sup>(Note4)</sup>						
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =-15V,V <sub>GS</sub> =0V, F=1.0MHz	-	909.5	-	PF
Output Capacitance	C <sub>OSS</sub>		-	90.3	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	71	-	PF
Switching Characteristics <sup>(Note 4)</sup>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-15V,I <sub>D</sub> =-4A V <sub>GS</sub> =-10V,R <sub>GEN</sub> =6Ω	-	7	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	3.5	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	35	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	10	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-15V,I <sub>D</sub> =-4A,V <sub>GS</sub> =-4.5V	-	7.3	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	1.1	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	2	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage <sup>(Note 3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-4A	-	-	-1.2	V

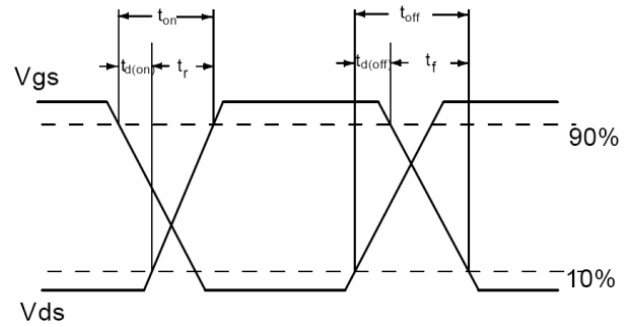
## Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

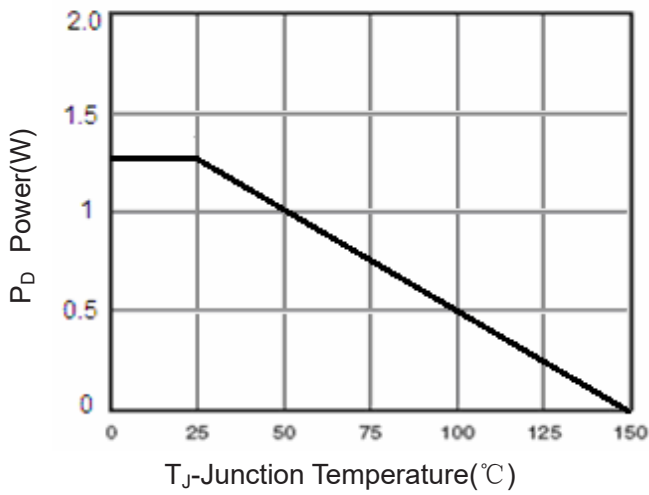
## Typical Electrical and Thermal Characteristics



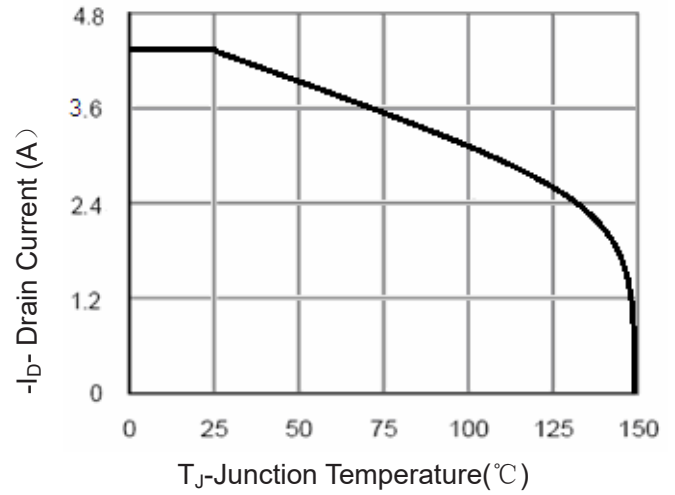
**Figure 1: Switching Test Circuit**



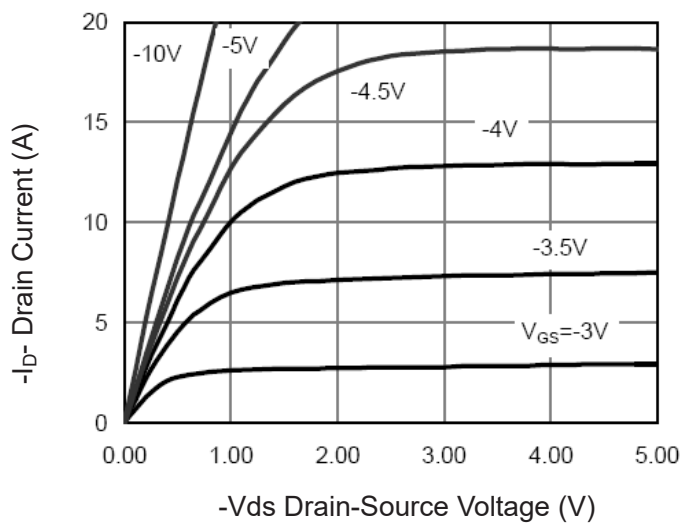
**Figure 2: Switching Waveforms**



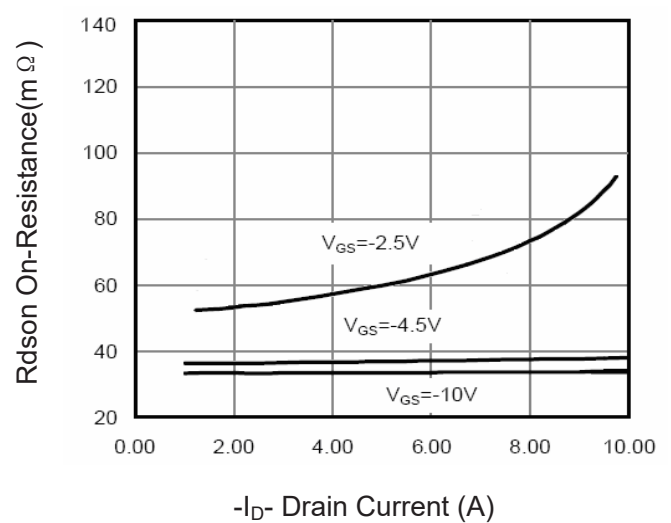
**Figure 3 Power Dissipation**



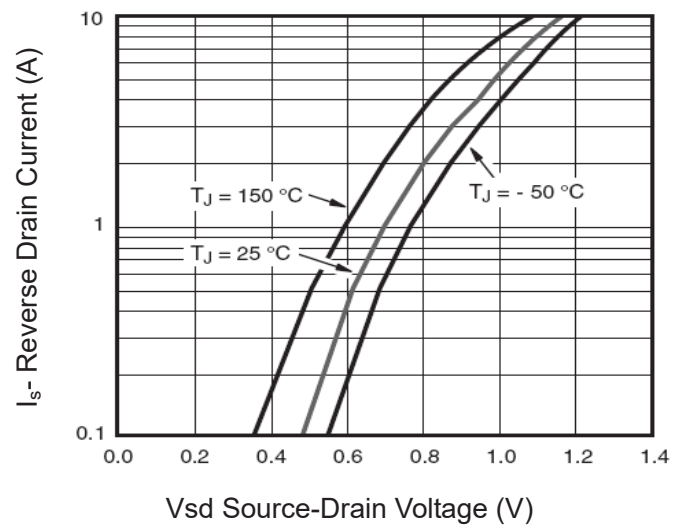
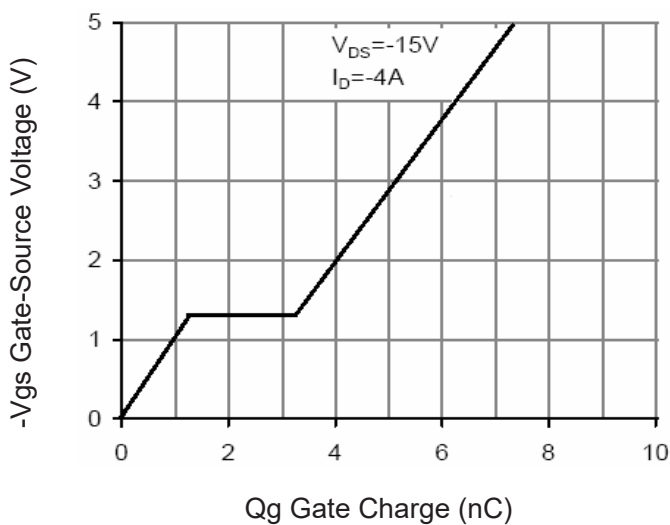
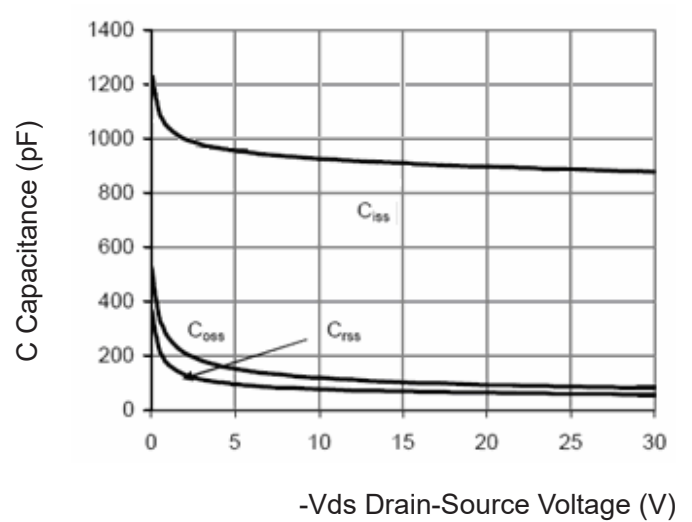
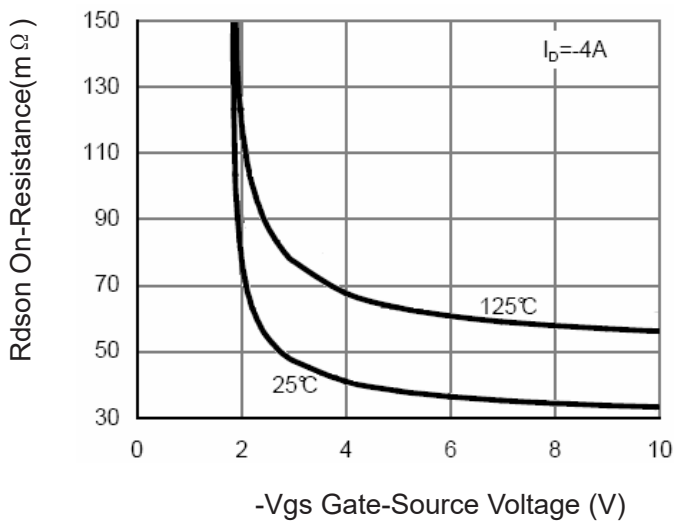
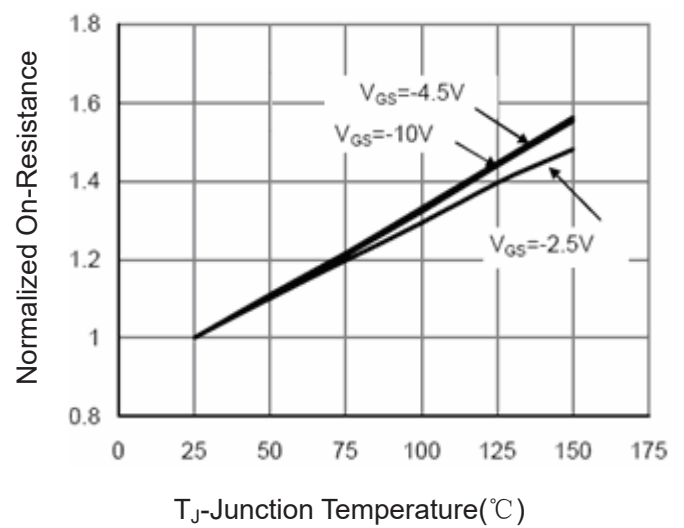
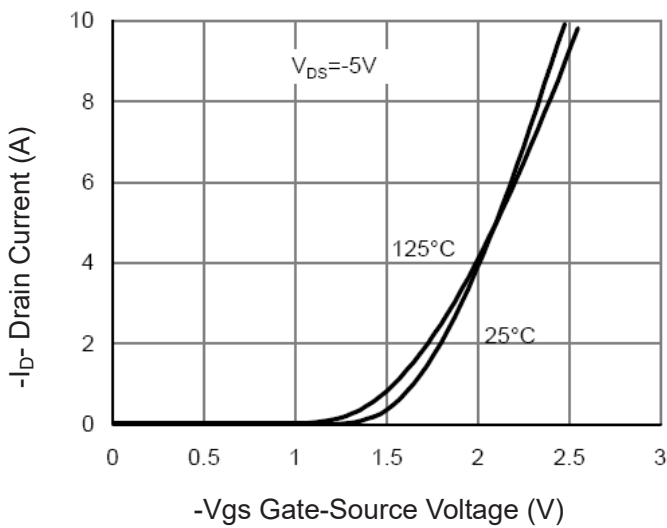
**Figure 4 Drain Current**

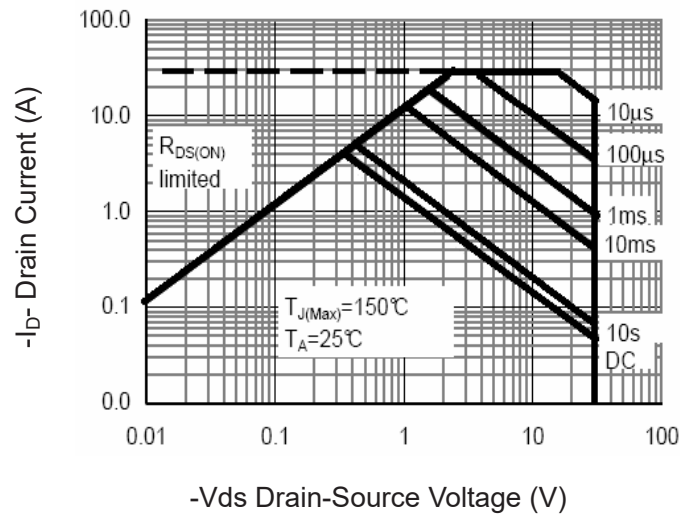


**Figure 5 Output Characteristics**

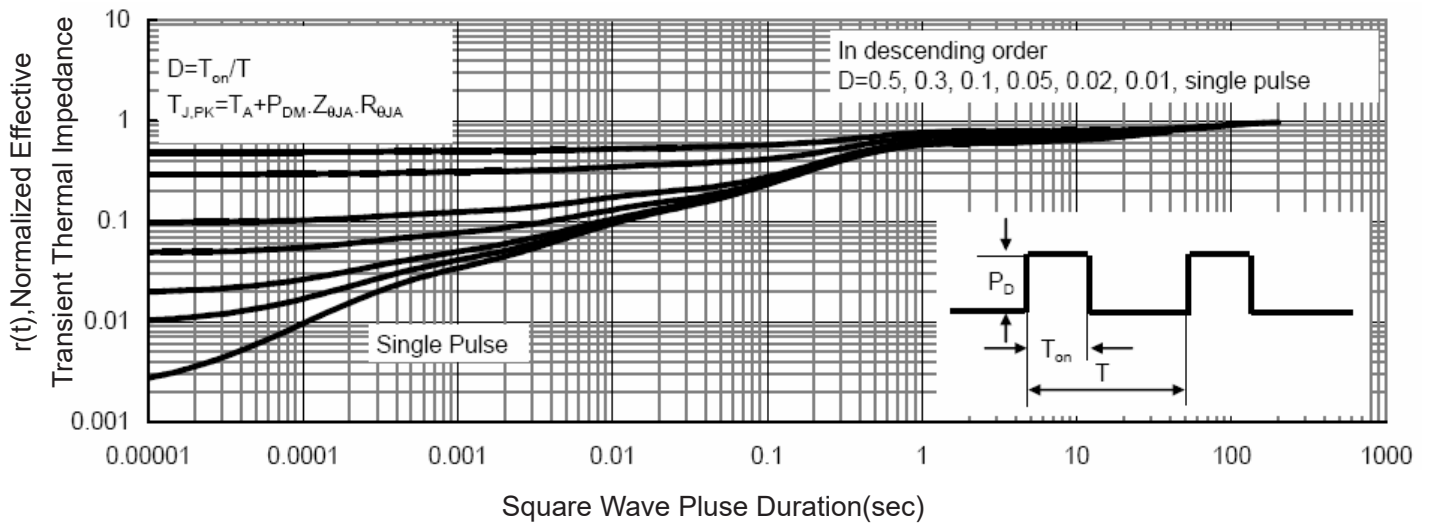


**Figure 6 Drain-Source On-Resistance**





**Figure 13 Safe Operation Area**



**Figure 14 Normalized Maximum Transient Thermal Impedance**